

THE COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

Sir:

Transmitted herewith for filing is the Utility patent application of:

Jeong-Goo YOON and Ju-Young PARK INVENTOR (s):

PROCESS FOR LAPPING WAFER AND MEHOD FOR PROCESSING BACKSIDE For: OF WAFER USING THE SAME

ATTORNEY DOCKET NUMBER: 2336-086

Enclosed are:

- □ 19 page(s) of Specification, Claims and Abstract
- ☐ informal drawings
- ☑ Declaration & Power of Attorney
- ☑ Claim of Priority under 35 U.S.C. § 119
- ☑ Certified copy of Korean Patent Application No. 2001-54519.
- An assignment conveying title in instant application to SAMSUNG ELECTRO-MECHANICS CO., LTD. with PTO Form 1595.
- ☑ Information Disclosure Statement
- ☑ Return Receipt Postcard

The filing fee is calculated as sl	10wn below	/:					
	NO. FILED			RATE	AMOUNT		
Total Claims	11	MINUS 20	0	x \$18 =	\$ 0.00		
Independent Claims	3	MINUS 3	0	x \$80 =	\$	0.00	
If multiple dependent claims are presented, add \$ 270.00							
Basic Fee							
□ Applicant claims small entity status. See 37 CFR 1.27. The fees indicated above are reduced by ½.							
Total of above calculations							
☑ Assignment and Recording Fee						40.00	
TOTAL FEE						780.00	

	Deposit Account N		the amount	of	to c	over th	e filing	and	assignmen
recordation fees. A	A duplicate copy of the	nis paper is enclose	d.						

☒ A credit card authorization for \$780.00 to cover the filing fees is enclosed.

The Commissioner is hereby authorized to charge any additional fees associated with this communication, including patent application filing fees and processing fees under 37 C.F.R § 1.16 and 1.17, or credit any overpayment to Deposit Account Number 07-1337.

nin J. Hauptman Redistration Number 29,310

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Date: December 10, 2001

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